



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

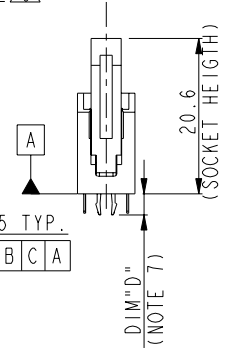
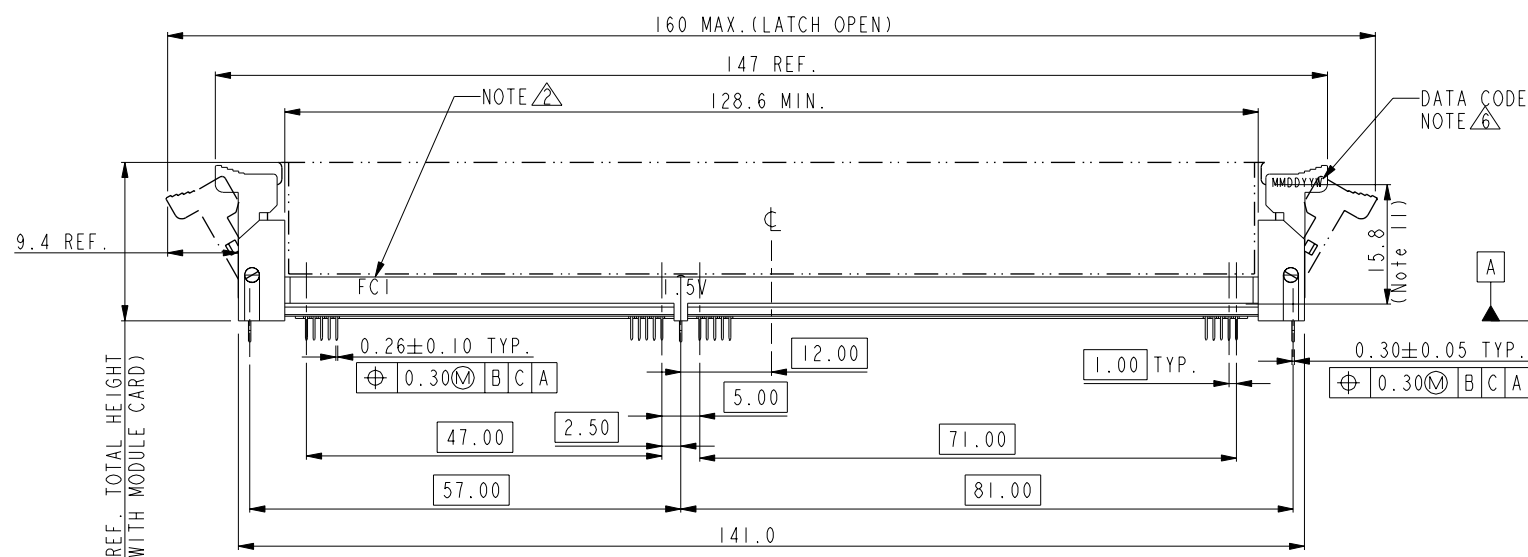
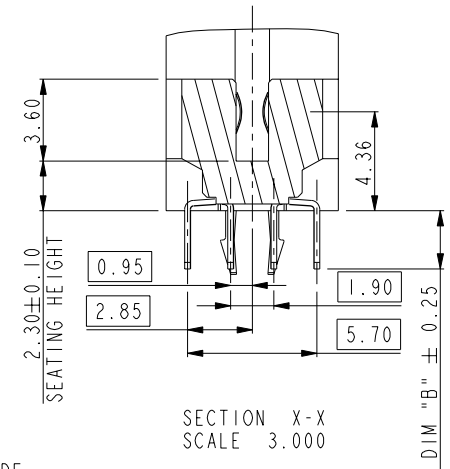
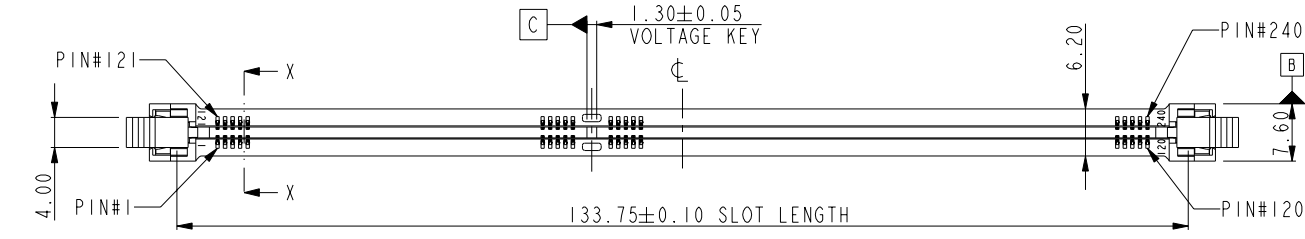
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

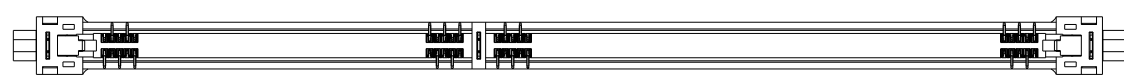




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20.95 REF. TOTAL HEIGHT (WITH MODULE CARD)



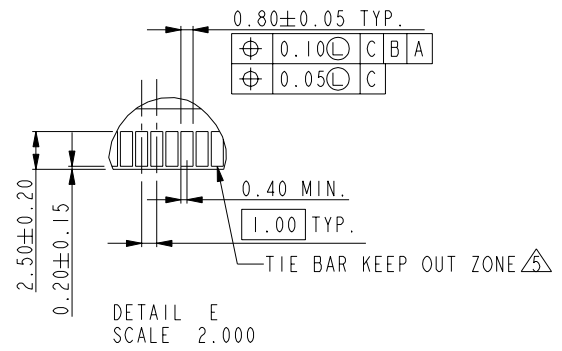
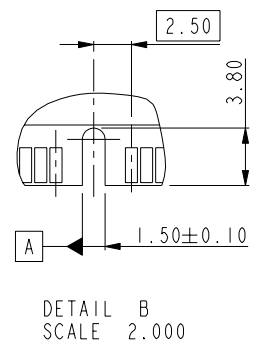
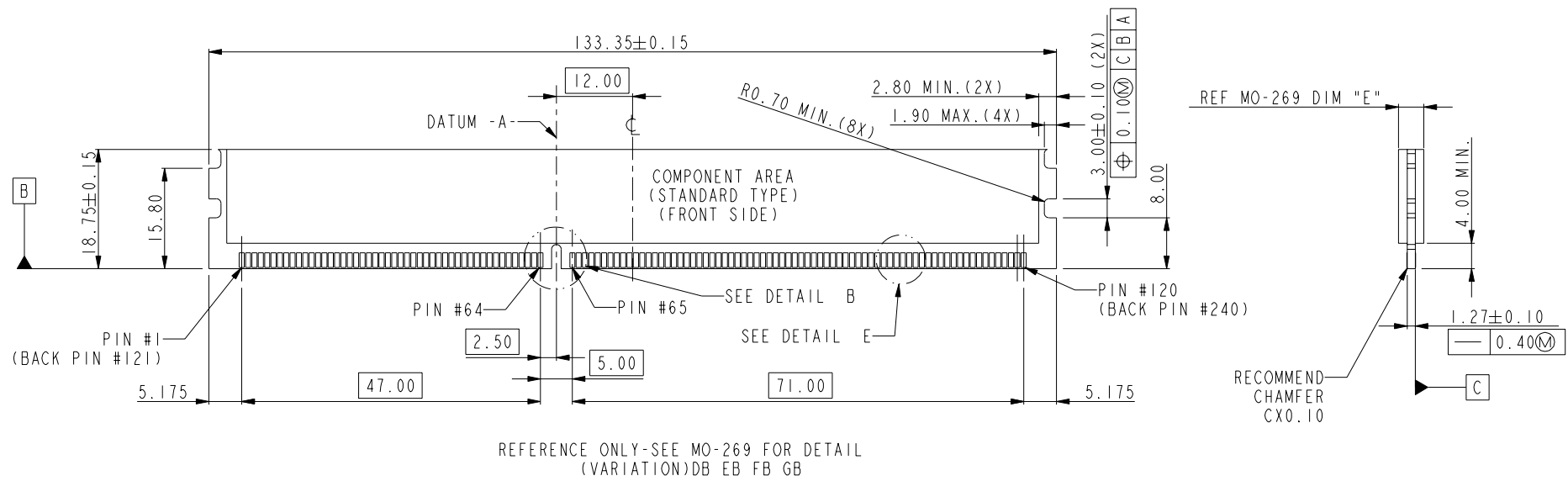
www.fciconnect.com		surface	<input checked="" type="checkbox"/>	tolerance std	projection	MM
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Dr	RICHARD CHIU	04/12/2007	ANGULAR	0.X	±0.38	size A4
Eng	RICHARD CHIU	04/12/2007	LINEAR	0.XX	±0.25	Scale 0.707
Chr	PAUL WANG	04/12/2007	0° ±5°	0.XXX	±0.13	ECN DG08-0233
Appr	JOSEPH HSIA	04/12/2007	Product family		-	Spec ref *
		title		10078239		Rev. D
		VERY LOW PROFILE (VLP) T.H				
		DDR3, 240P MEMORY SOCKET (FOR UDIMM)				
		catalog no		CUSTOMER		sheet 1 of 4

rev	ecn no	dr	date
A	DG08-0020	R C	01/14/2008
B	DG08-0064	R C	03/20/2008
C	DG08-0200	R C	07/31/2008
D	T09-1069	R C	05/13/2009
-	-	-	-
-	-	-	-
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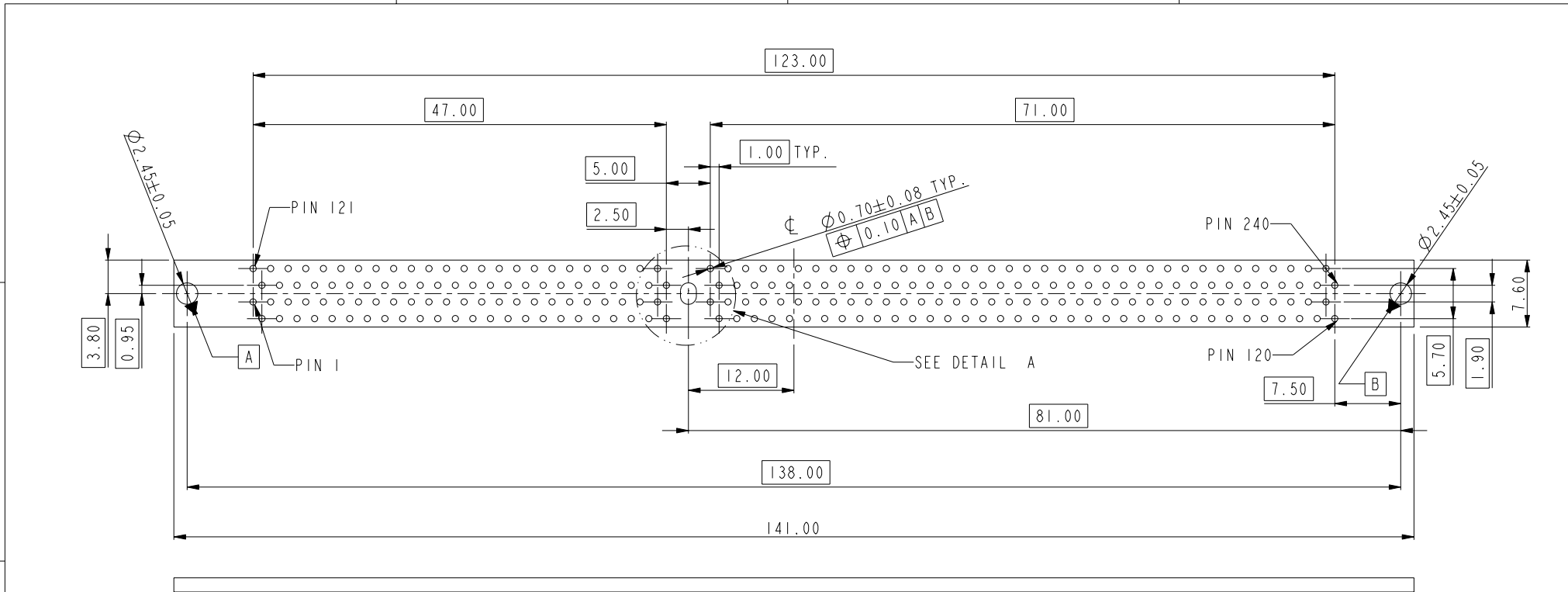


www.fciconnect.com		surface	-	tolerance std		projection	MM
		TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	RICHARD CHIU	04/12/2007	ANGULAR	0.X	±0.38	size	A4
Eng	RICHARD CHIU	04/12/2007	LINEAR	0.XX	±0.25	Scale	1.000
Chr	PAUL WANG	04/12/2007	0° ±5°	0.XXX	±0.13	ECN	DG08-0233
Appr	JOSEPH HSIA	04/12/2007	Product family		-	Spec ref	*
FCI		title		VERY LOW PROFILE (VLP) T.H		dwg no	
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		catalog no		-		CUSTOMER	
						sheet 2 of 4	

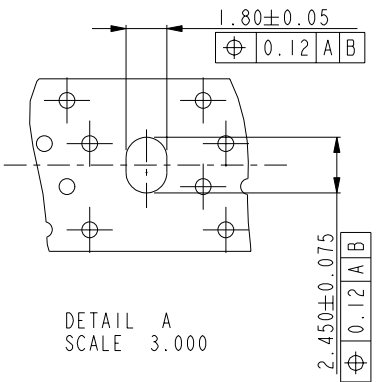
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RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



www.fciconnect.com				surface	<input checked="" type="checkbox"/>	tolerance std	projection	MM
				TOLERANCES UNLESS OTHERWISE SPECIFIED				
Dr	RICHARD CHIU	04/12/2007	ANGULAR	LINEAR	0.X	± 0.38	size	A4
Eng	RICHARD CHIU	04/12/2007			0.XX	± 0.25		Scale
Chr	PAUL WANG	04/12/2007	0°	$\pm 5^\circ$	0.XXX	± 0.13	ECN	DG08-0233
Appr	JOSEPH HSIA	04/12/2007	Product family				Spec ref	*
FCI			title		VERY LOW PROFILE (VLP) T.H		dwg no	
					DDR3, 240P MEMORY SOCKET (FOR UDIMM)		10078239	
					catalog no		CUSTOMER	
							sheet 3 of 4	
							Rev. D	

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10078239 - □ □ □ □

STYLE : MECHANICAL KEYING
1 : 1.5 VOLT. W/ CENTER KEY

CONTACT & FORKLOCK LENGTH

CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 MM (0.063")
11	3.18 mm	4.00 mm	2.36 MM (0.093")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
1LF	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
2LF	15u" (0.38um) MIN. GOLD		
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 2 : BLACK HOUSING + BLACK EJECTOR
- 8 : IVORY HOUSING + IVORY EJECTOR
- 9 : IVORY HOUSING + BLACK EJECTOR



- NOTES:
1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
TERMINAL: HIGH PERFORMANCE COPPER ALLOY
METAL CLIP: COPPER ALLOY.
 2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
 3. PRODUCT SPECIFICATION: GS-12-368.
 4. PACKAGING SPECIFICATION: GS-14-899.
 5. FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
 6. THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE.
 7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
 8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X.(SUSPENDED BY JEDEC)
 9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 10. THE HOUSING WILL WITH STAND EXPOSURE TO 260 ± 5°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
 11. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.

www.fciconnect.com			surface <input checked="" type="checkbox"/>	tolerance std	projection	MM		
			TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	RICHARD CHIU	04/12/2007	ANGULAR	LINEAR	0.X	±0.38	size A4	Scale 1.000
Eng	RICHARD CHIU	04/12/2007			0.XX	±0.25	ECN	DG08-0233
Chr	PAUL WANG	04/12/2007			0°	±5°		
Appr	JOSEPH HSIA	04/12/2007	Product family			Spec ref *		
		VERY LOW PROFILE (VLP) T.H			dwg no	10078239		Rev. D
		DDR3, 240P MEMORY SOCKET (FOR UDIMM)			catalog no	CUSTOMER		sheet 4 of 4

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